

RPD 装置ラインアップ



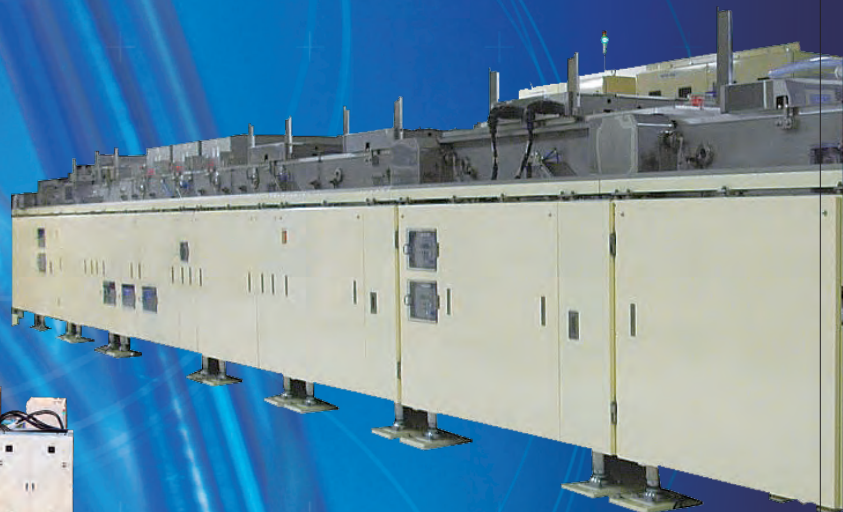
Line-up of Reactive Plasma Deposition (RPD) equipment

量産装置

(In-Line Type)

Mass Production Line

Substrate size: 550 mm×650mm
800mm×1000mm
1200mm×1800mm



RPD equipment features

- ◆ High throughput due to high deposition rate by high density arc plasma
- ◆ High quality Transparent Conductive Oxide (TCO) films can be deposited at a high deposition rate at any substrate temperature compared with conventional sputtering methods
- ◆ High availability by material supplying system without stopping deposition operation
- ◆ Low C.O.O. by low cost material and high material use efficiency
- ◆ Small foot print due to smaller number of coating sources than conventional sputtering equipments

パイロット装置

Prototype Production Line

Substrate size: 200mm×200mm
300mm×400mm
370mm×480mm



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高品質透明電極成膜を実現する RPD 装置



SUMITOMO-RPD realizes a High Quality TCO films deposition

❖ 低抵抗・高透過率 TCO 成膜

- 200℃以下の低温成膜運転条件下で、低抵抗・高透過率な TCO 成膜を実現

Low resistivity and high visible transmittance ITO or ZnO films can be deposited under low substrate temperature, e.g. below 200℃.

❖ 低ダメージ成膜プロセス

- 下地層に対する低ダメージ成膜が可能

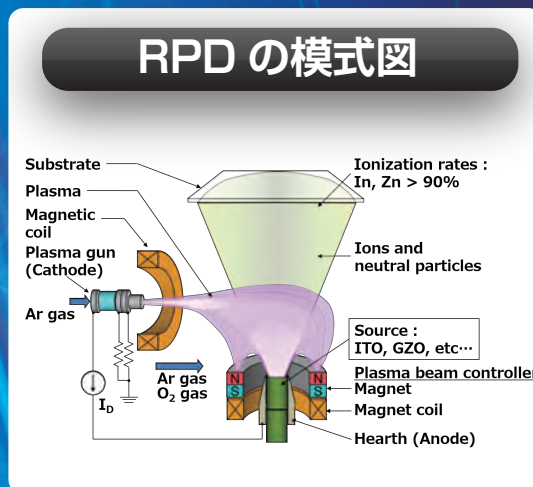
RPD is a damage-free deposition method because no high energy particles (>70eV) are involved in the process.

❖ 連続真空稼働時間(実績:~3週間)

- 成膜材料供給装置により、真空を維持したまま連続稼働が可能
Material supplying system realizes continuous running without maintenance for 3 weeks.

❖ 基板高速処理インラインシステム

- 高速成膜レートをいかした高速基板搬送技術
RPD equipment has the stable high-speed substrate conveyance system corresponding to the high deposition rate

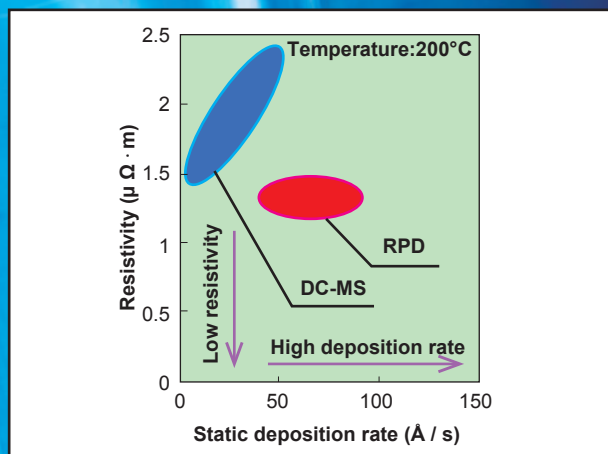
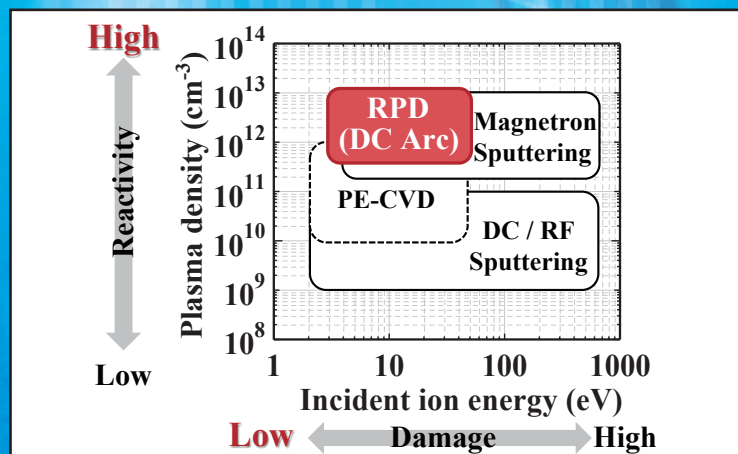


プラズマ成膜におけるRPD法の特徴

Characteristics of the SUMITOMO-RPD as a plasma coating method

RPD-ITOとDCMS-ITOの比較

Comparison of characteristics of RPD-ITO and DCMS-ITO



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